

## WAFER PROCESSING METHOD

### ABSTRACT

A wafer processing method for processing a wafer includes a reverse side which has an annular protruding portion on an outer circumferential portion thereof and a circular recessed portion in a region surrounded by the annular protruding portion on the reverse side, in which a sheet including no glue layer is fixed to a face side of the wafer and an annular frame is fixed to an outer circumferential portion of the sheet to form a wafer unit, the wafer is held on a holding table via the sheet, a dividing groove is formed in the circular recessed portion of the wafer, the annular protruding portion is separated from the wafer, and the annular protruding portion is removed from the sheet.

[FIG. 4]